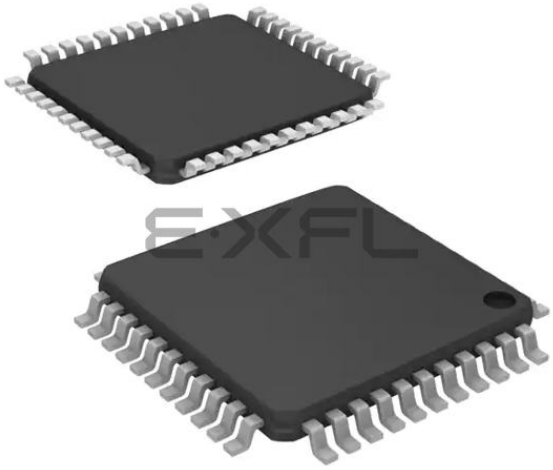
Microchip Technology - PIC32MX150F128D-V/PT Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx150f128d-v-pt

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUs

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX 28/36/44-pin Family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 "Decoupling Capacitors"**)
- VCAP pin (see **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.7 "External Oscillator Pins"**)

The following pins may be required:

- VREF+/VREF- pins – used when external voltage reference for the ADC module is implemented

Note: The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

4.2 Bus Matrix Control Registers

TABLE 4-2: BUS MATRIX REGISTER MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	BMXCON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	BMXERRIXI	BMXERRICD	BMXERRDMA	BMXERRDS	BMXERRIS	001F
		15:0	—	—	—	—	—	—	—	—	—	BMXWSDRM	—	—	—	BMXARB<2:0>			0041
2010	BMXDKPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDKPBA<15:0>																0000
2020	BMXDUDBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUDBA<15:0>																0000
2030	BMXDUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BMXDUPBA<15:0>																0000
2040	BMXDRMSZ	31:16	BMXDRMSZ<31:0>																xxxx
		15:0																	xxxx
2050	BMXPUPBA(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	BMXPUPBA<19:16>				0000
		15:0	BMXPUPBA<15:0>																0000
2060	BMXPFMSZ	31:16	BMXPFMSZ<31:0>																xxxx
		15:0																	xxxx
2070	BMXBOOTSZ	31:16	BMXBOOTSZ<31:0>																0000
		15:0																	0C00

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

NOTES:

REGISTER 6-1: RCON: RESET CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS	R/W-0
	—	—	—	—	—	—	CMR	VREGS
7:0	R/W-0, HS	R/W-0, HS	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-1, HS	R/W-1, HS
	EXTR	SWR	—	WDTO	SLEEP	IDLE	BOR(1)	POR(1)

Legend:	HS = Set by hardware		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-10 **Unimplemented:** Read as '0'

bit 9 **CMR:** Configuration Mismatch Reset Flag bit
1 = Configuration mismatch Reset has occurred
0 = Configuration mismatch Reset has not occurred

bit 8 **VREGS:** Voltage Regulator Standby Enable bit
1 = Regulator is enabled and is on during Sleep mode
0 = Regulator is disabled and is off during Sleep mode

bit 7 **EXTR:** External Reset ($\overline{MCLR}$) Pin Flag bit
1 = Master Clear (pin) Reset has occurred
0 = Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset Flag bit
1 = Software Reset was executed
0 = Software Reset as not executed

bit 5 **Unimplemented:** Read as '0'

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT Time-out has occurred
0 = WDT Time-out has not occurred

bit 3 **SLEEP:** Wake From Sleep Flag bit
1 = Device was in Sleep mode
0 = Device was not in Sleep mode

bit 2 **IDLE:** Wake From Idle Flag bit
1 = Device was in Idle mode
0 = Device was not in Idle mode

bit 1 **BOR:** Brown-out Reset Flag bit(1)
1 = Brown-out Reset has occurred
0 = Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit(1)
1 = Power-on Reset has occurred
0 = Power-on Reset has not occurred

Note 1: User software must clear this bit to view next detection.

9.0 DIRECT MEMORY ACCESS (DMA) CONTROLLER

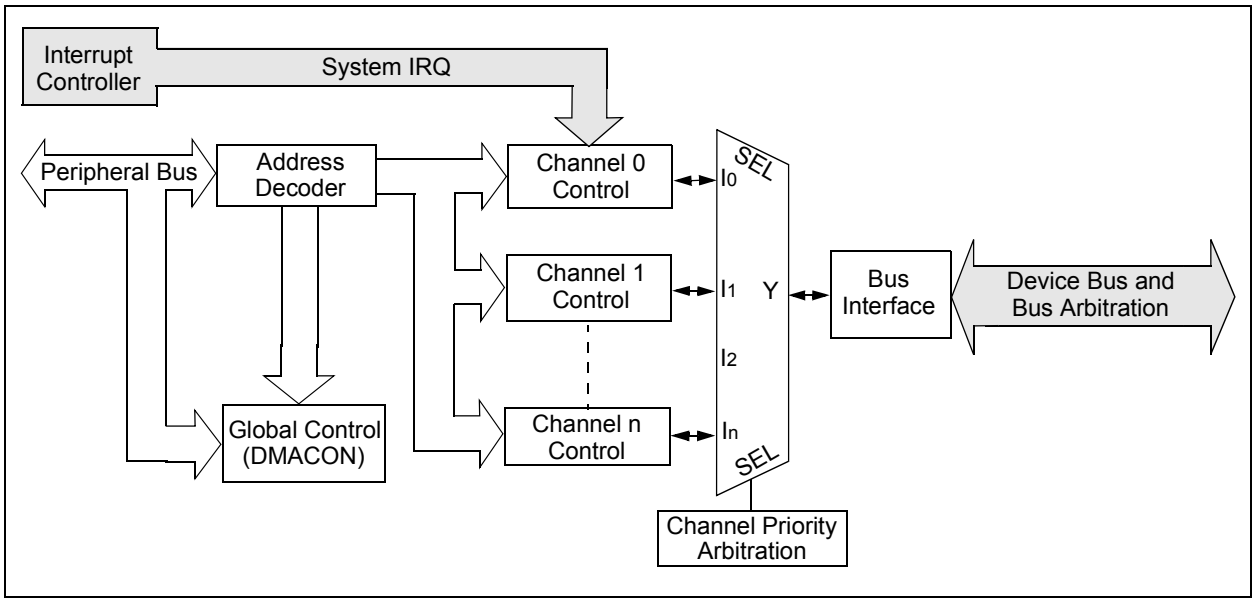
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 31. "Direct Memory Access (DMA) Controller"** (DS60001117), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 Direct Memory Access (DMA) controller is a bus master module useful for data transfers between different devices without CPU intervention. The source and destination of a DMA transfer can be any of the memory mapped modules existent in the PIC32, such as Peripheral Bus devices: SPI, UART, PMP, etc., or memory itself. Figure 9-1 show a block diagram of the DMA Controller module.

The DMA Controller module has the following key features:

- Four identical channels, each featuring:
  - Auto-increment source and destination address registers
  - Source and destination pointers
  - Memory to memory and memory to peripheral transfers
- Automatic word-size detection:
  - Transfer granularity, down to byte level
  - Bytes need not be word-aligned at source and destination
- Fixed priority channel arbitration
- Flexible DMA channel operating modes:
  - Manual (software) or automatic (interrupt) DMA requests
  - One-Shot or Auto-Repeat Block Transfer modes
  - Channel-to-channel chaining
- Flexible DMA requests:
  - A DMA request can be selected from any of the peripheral interrupt sources
  - Each channel can select any (appropriate) observable interrupt as its DMA request source
  - A DMA transfer abort can be selected from any of the peripheral interrupt sources
  - Pattern (data) match transfer termination
- Multiple DMA channel status interrupts:
  - DMA channel block transfer complete
  - Source empty or half empty
  - Destination full or half full
  - DMA transfer aborted due to an external event
  - Invalid DMA address generated
- DMA debug support features:
  - Most recent address accessed by a DMA channel
  - Most recent DMA channel to transfer data
- CRC Generation module:
  - CRC module can be assigned to any of the available channels
  - CRC module is highly configurable

FIGURE 9-1: DMA BLOCK DIAGRAM



REGISTER 9-9: DCHxINT: DMA CHANNEL 'x' INTERRUPT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-24 **Unimplemented:** Read as '0'

bit 23 **CHSDIE:** Channel Source Done Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 22 **CHSHIE:** Channel Source Half Empty Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 21 **CHDDIE:** Channel Destination Done Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 20 **CHDHIE:** Channel Destination Half Full Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 19 **CHBCIE:** Channel Block Transfer Complete Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 18 **CHCCIE:** Channel Cell Transfer Complete Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 17 **CHTAIE:** Channel Transfer Abort Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 16 **CHERIE:** Channel Address Error Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **CHSDIF:** Channel Source Done Interrupt Flag bit
- 1 = Channel Source Pointer has reached end of source (CHSPTR = CHSSIZ)
- 0 = No interrupt is pending

bit 6 **CHSHIF:** Channel Source Half Empty Interrupt Flag bit
- 1 = Channel Source Pointer has reached midpoint of source (CHSPTR = CHSSIZ/2)
- 0 = No interrupt is pending

bit 5 **CHDDIF:** Channel Destination Done Interrupt Flag bit
- 1 = Channel Destination Pointer has reached end of destination (CHDPTR = CHDSIZ)
- 0 = No interrupt is pending

10.0 USB ON-THE-GO (OTG)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 27. "USB On-The-Go (OTG)"** (DS60001126), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The Universal Serial Bus (USB) module contains analog and digital components to provide a USB 2.0 Full-Speed and Low-Speed embedded host, Full-Speed device or OTG implementation with a minimum of external components. This module in Host mode is intended for use as an embedded host and therefore does not implement a UHCI or OHCI controller.

The USB module consists of the clock generator, the USB voltage comparators, the transceiver, the Serial Interface Engine (SIE), a dedicated USB DMA controller, pull-up and pull-down resistors, and the register interface. A block diagram of the PIC32 USB OTG module is presented in Figure 10-1.

The clock generator provides the 48 MHz clock required for USB Full-Speed and Low-Speed communication. The voltage comparators monitor the voltage on the VBUS pin to determine the state of the bus. The transceiver provides the analog translation between the USB bus and the digital logic. The SIE is a state machine that transfers data to and from the endpoint buffers and generates the hardware protocol for data transfers. The USB DMA controller transfers data between the data buffers in RAM and the SIE. The integrated pull-up and pull-down resistors eliminate the need for external signaling components. The register interface allows the CPU to configure and communicate with the module.

The PIC32 USB module includes the following features:

- USB Full-Speed support for Host and Device
- Low-Speed Host support
- USB OTG support
- Integrated signaling resistors
- Integrated analog comparators for VBUS monitoring
- Integrated USB transceiver
- Transaction handshaking performed by hardware
- Endpoint buffering anywhere in system RAM
- Integrated DMA to access system RAM and Flash

Note: The implementation and use of the USB specifications, as well as other third party specifications or technologies, may require licensing; including, but not limited to, USB Implementers Forum, Inc., also referred to as USB-IF (www.usb.org). The user is fully responsible for investigating and satisfying any applicable licensing obligations.

17.0 SERIAL PERIPHERAL INTERFACE (SPI)

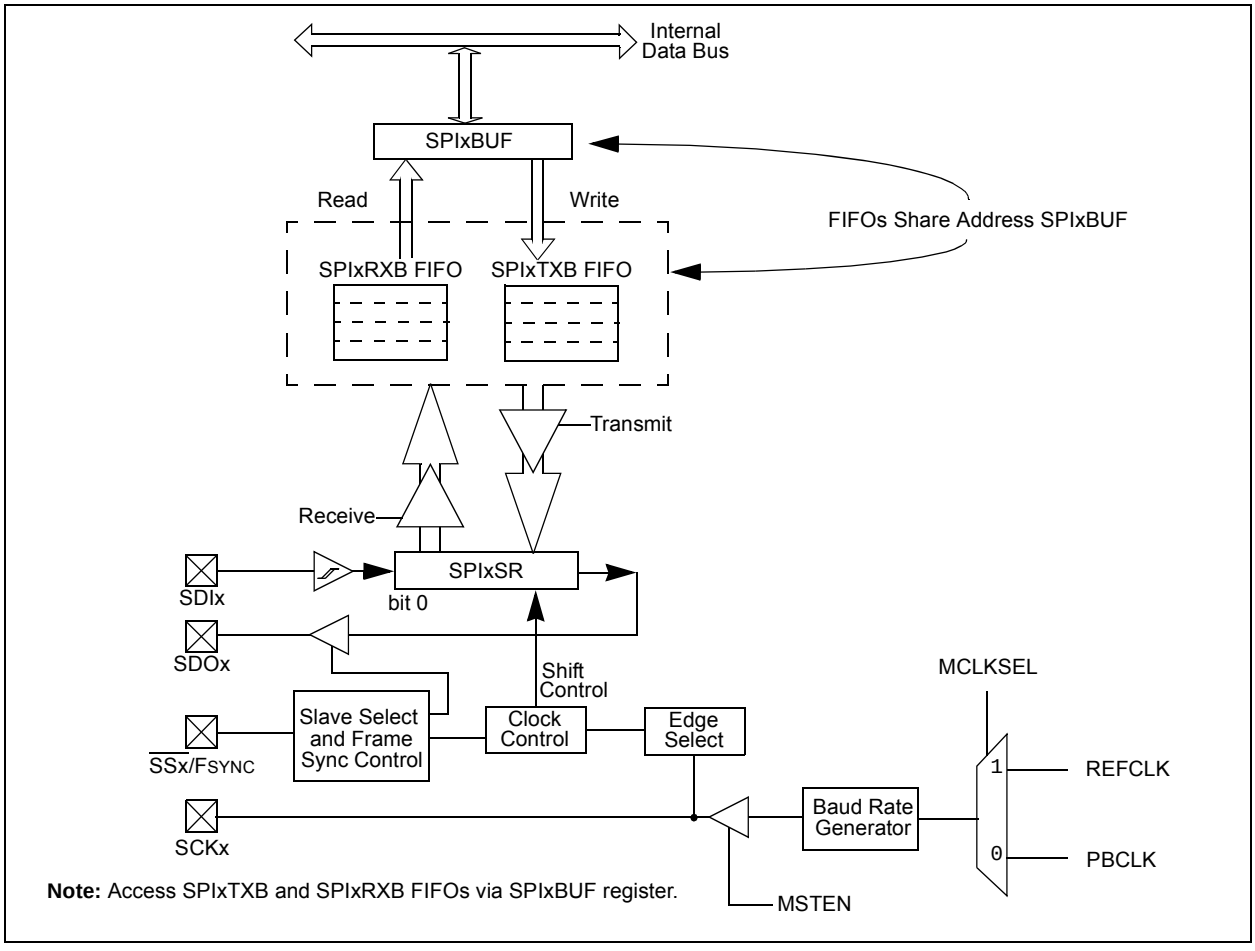
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 23. "Serial Peripheral Interface (SPI)"** (DS60001106), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The SPI module is a synchronous serial interface that is useful for communicating with external peripherals and other microcontrollers. These peripheral devices may be Serial EEPROMs, Shift registers, display drivers, Analog-to-Digital Converters (ADC), etc. The PIC32 SPI module is compatible with Motorola® SPI and SIOP interfaces.

Some of the key features of the SPI module are:

- Master mode and Slave mode support
- Four clock formats
- Enhanced Framed SPI protocol support
- User-configurable 8-bit, 16-bit and 32-bit data width
- Separate SPI FIFO buffers for receive and transmit
  - FIFO buffers act as 4/8/16-level deep FIFOs based on 32/16/8-bit data width
- Programmable interrupt event on every 8-bit, 16-bit and 32-bit data transfer
- Operation during Sleep and Idle modes
- Audio Codec Support:
  - I^2S protocol
  - Left-justified
  - Right-justified
  - PCM

FIGURE 17-1: SPI MODULE BLOCK DIAGRAM



REGISTER 17-1: SPIxCON: SPI CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FRMEN	FRMSYNC	FRMPOL	MSSEN	FRMSYPW	FRMCNT<2:0>		
23:16	R/W-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	MCLKSEL(2)	—	—	—	—	—	SPIFE	ENHBUF(2)
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ON(1)	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE(3)
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	SSEN	CKP(4)	MSTEN	DISSDI	STXISEL<1:0>		SRXISEL<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **FRMEN:** Framed SPI Support bit
1 = Framed SPI support is enabled ($\overline{SSx}$ pin used as FSYNC input/output)
0 = Framed SPI support is disabled

bit 30 **FRMSYNC:** Frame Sync Pulse Direction Control on $\overline{SSx}$ pin bit (Framed SPI mode only)
1 = Frame sync pulse input (Slave mode)
0 = Frame sync pulse output (Master mode)

bit 29 **FRMPOL:** Frame Sync Polarity bit (Framed SPI mode only)
1 = Frame pulse is active-high
0 = Frame pulse is active-low

bit 28 **MSSEN:** Master Mode Slave Select Enable bit
1 = Slave select SPI support enabled. The $\overline{SS}$ pin is automatically driven during transmission in Master mode. Polarity is determined by the FRMPOL bit.
0 = Slave select SPI support is disabled.

bit 27 **FRMSYPW:** Frame Sync Pulse Width bit
1 = Frame sync pulse is one character wide
0 = Frame sync pulse is one clock wide

bit 26-24 **FRMCNT<2:0>:** Frame Sync Pulse Counter bits. Controls the number of data characters transmitted per pulse. This bit is only valid in FRAMED_SYNC mode.
111 = Reserved; do not use
110 = Reserved; do not use
101 = Generate a frame sync pulse on every 32 data characters
100 = Generate a frame sync pulse on every 16 data characters
011 = Generate a frame sync pulse on every 8 data characters
010 = Generate a frame sync pulse on every 4 data characters
001 = Generate a frame sync pulse on every 2 data characters
000 = Generate a frame sync pulse on every data character

bit 23 **MCLKSEL:** Master Clock Enable bit(2)
1 = REFCLK is used by the Baud Rate Generator
0 = PBCLK is used by the Baud Rate Generator

bit 22-18 **Unimplemented:** Read as '0'

Note 1: When using the 1:1 PBCLK divisor, the user's software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit can only be written when the ON bit = 0.

3: This bit is not used in the Framed SPI mode. The user should program this bit to '0' for the Framed SPI mode (FRMEN = 1).

4: When AUDEN = 1, the SPI module functions as if the CKP bit is equal to '1', regardless of the actual value of CKP.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 10 **EDGSEQEN:** Edge Sequence Enable bit
1 = Edge1 must occur before Edge2 can occur
0 = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit(2)
1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 8 **CTTRIG:** Trigger Control bit
1 = Trigger output is enabled
0 = Trigger output is disabled

bit 7-2 **ITRIM<5:0>:** Current Source Trim bits
011111 = Maximum positive change from nominal current
011110
•
•
•
000001 = Minimum positive change from nominal current
000000 = Nominal current output specified by IRNG<1:0>
111111 = Minimum negative change from nominal current
•
•
•
100010
100001 = Maximum negative change from nominal current

bit 1-0 **IRNG<1:0>:** Current Range Select bits(3)
11 = 100 times base current
10 = 10 times base current
01 = Base current level
00 = 1000 times base current(4)

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 "Electrical Characteristics"** for current values.

4: This bit setting is not available for the CTMU temperature diode.

27.3 On-Chip Voltage Regulator

All PIC32MX1XX/2XX 28/36/44-pin Family devices' core and digital logic are designed to operate at a nominal 1.8V. To simplify system designs, most devices in the PIC32MX1XX/2XX 28/36/44-pin Family family incorporate an on-chip regulator providing the required core logic voltage from VDD.

A low-ESR capacitor (such as tantalum) must be connected to the VCAP pin (see Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in **Section 30.1 "DC Characteristics"**.

Note:	It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

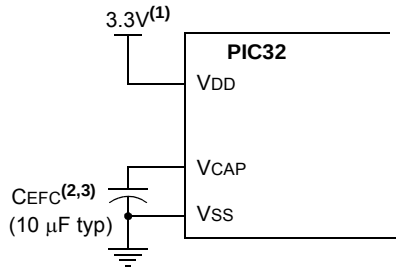
27.3.1 ON-CHIP REGULATOR AND POR

It takes a fixed delay for the on-chip regulator to generate an output. During this time, designated as TPU, code execution is disabled. TPU is applied every time the device resumes operation after any power-down, including Sleep mode.

27.3.2 ON-CHIP REGULATOR AND BOR

PIC32MX1XX/2XX 28/36/44-pin Family devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain a regulated level, the regulator Reset circuitry will generate a Brown-out Reset. This event is captured by the BOR flag bit (RCON<1>). The brown-out voltage levels are specific in **Section 30.1 "DC Characteristics"**.

FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 30.1 "DC Characteristics"** for the full operating ranges of VDD.

2: It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

3: The typical voltage on the VCAP pin is 1.8V.

27.4 Programming and Diagnostics

PIC32MX1XX/2XX 28/36/44-pin Family devices provide a complete range of programming and diagnostic features that can increase the flexibility of any application using them. These features allow system designers to include:

- Simplified field programmability using two-wire In-Circuit Serial Programming™ (ICSP™) interfaces
- Debugging using ICSP
- Programming and debugging capabilities using the EJTAG extension of JTAG
- JTAG boundary scan testing for device and board diagnostics

PIC32 devices incorporate two programming and diagnostic modules, and a trace controller, that provide a range of functions to the application developer.

Figure 27-2 illustrates a block diagram of the programming, debugging, and trace ports.

FIGURE 27-2: BLOCK DIAGRAM OF PROGRAMMING, DEBUGGING AND TRACE PORTS

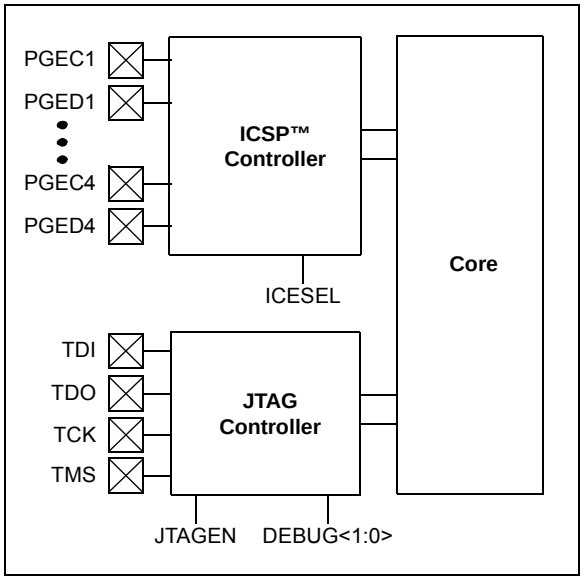


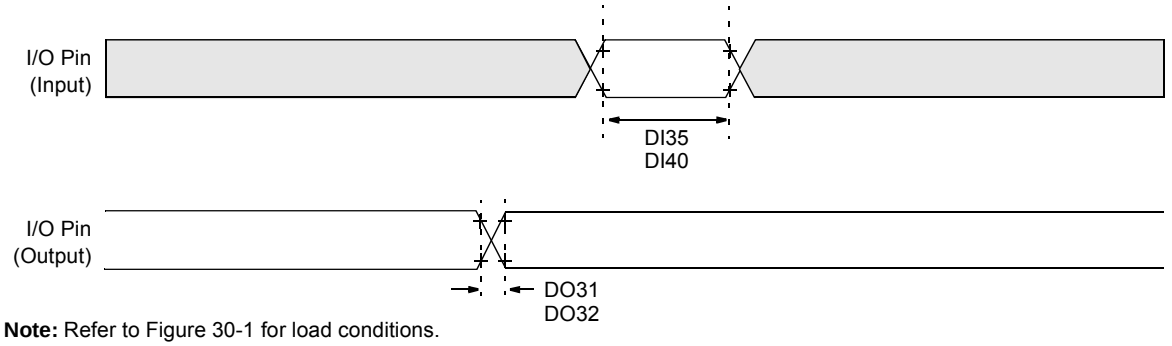
TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage (Note 2)**	2.3	—	3.6	V	—
DC12	VDR	**RAM Data Retention Voltage (Note 1)**	1.75	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	1.75	—	2.1	V	—
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.00005	—	0.115	V/μs	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 30-11 for BOR values.

FIGURE 30-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(2)**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DO32	TIOF	Port Output Fall Time	—	5	15	ns	VDD < 2.5V
			—	5	10	ns	VDD > 2.5V
DI35	TINP	INTx Pin High or Low Time	10	—	—	ns	—
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TSYSCLK	—

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: This parameter is characterized, but not tested in manufacturing.

FIGURE 30-20: PARALLEL SLAVE PORT TIMING

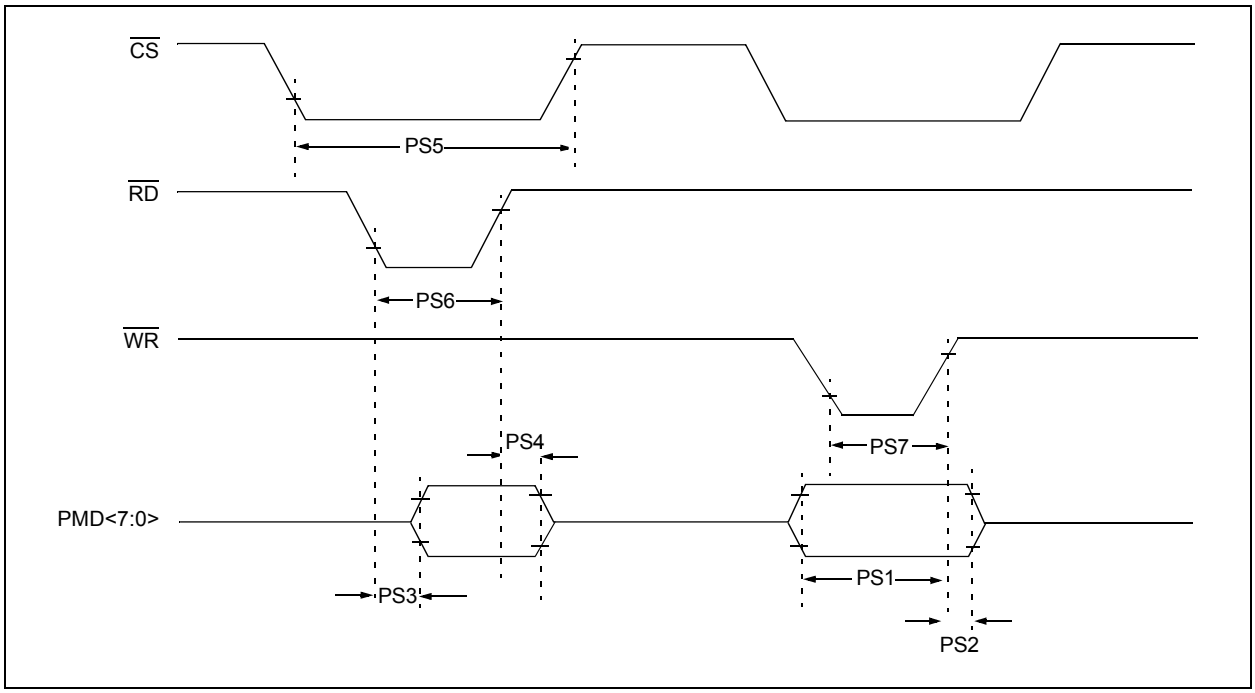


TABLE 31-5: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
MOS10	FOSC	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 50	MHz MHz	EC **(Note 2)** ECPLL **(Note 1)**

Note 1: PLL input requirements: 4 MHz ≤ FPLLIN ≤ 5 MHz (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.

2: This parameter is characterized, but not tested in manufacturing.

TABLE 31-6: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
MSP10	TscL	SCKx Output Low Time **(Note 1,2)**	TSCK/2	—	—	ns	—
MSP11	TscH	SCKx Output High Time **(Note 1,2)**	TSCK/2	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

TABLE 31-7: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MSP10	TscL	SCKx Output Low Time **(Note 1,2)**	TSCK/2	—	—	ns	—
MSP11	TscH	SCKx Output High Time **(Note 1,2)**	TSCK/2	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

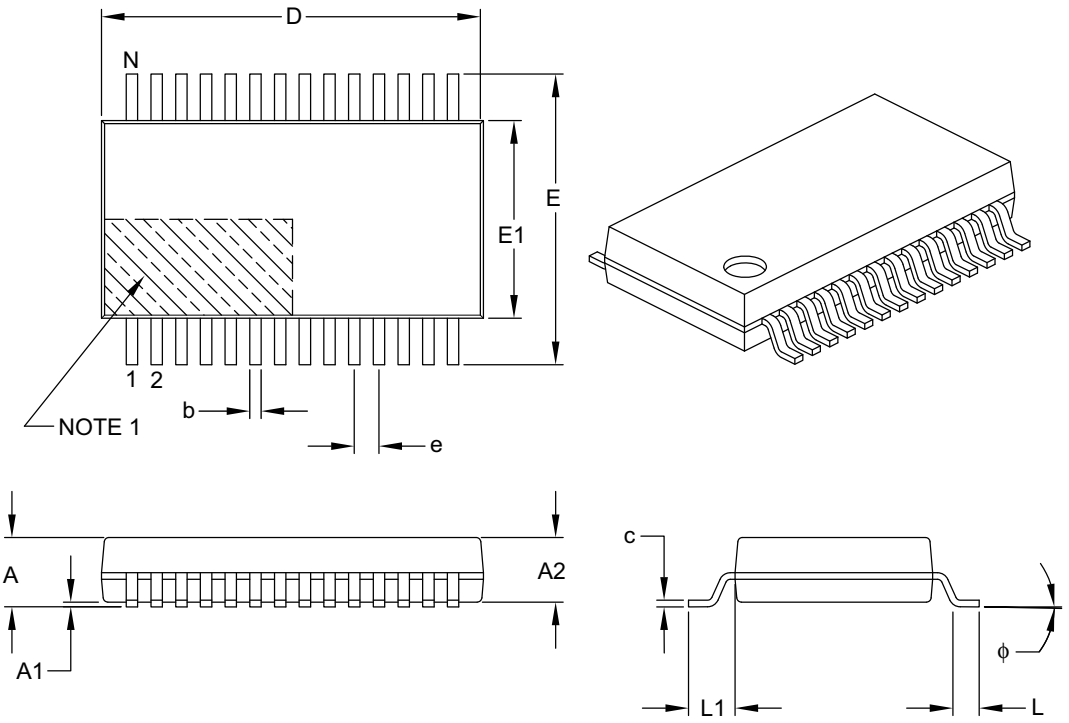
2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

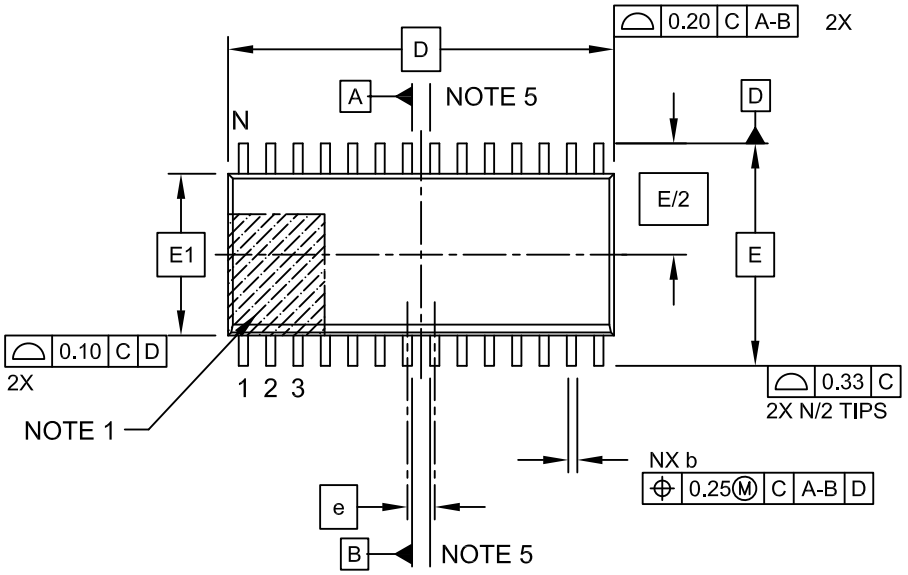
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

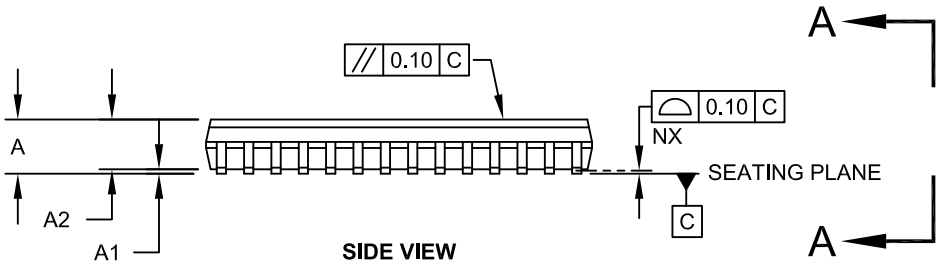
Microchip Technology Drawing C04-073B

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

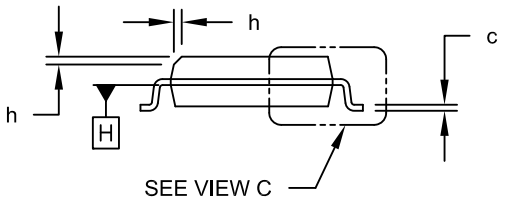
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

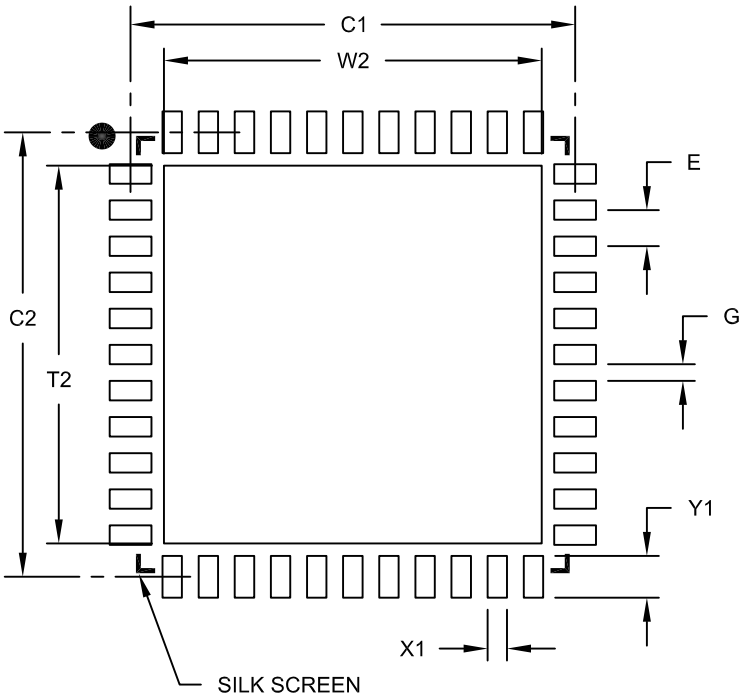


VIEW A-A

Microchip Technology Drawing C04-052C Sheet 1 of 2

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			6.80
Optional Center Pad Length	T2			6.80
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.80
Distance Between Pads	G	0.25		

Notes:

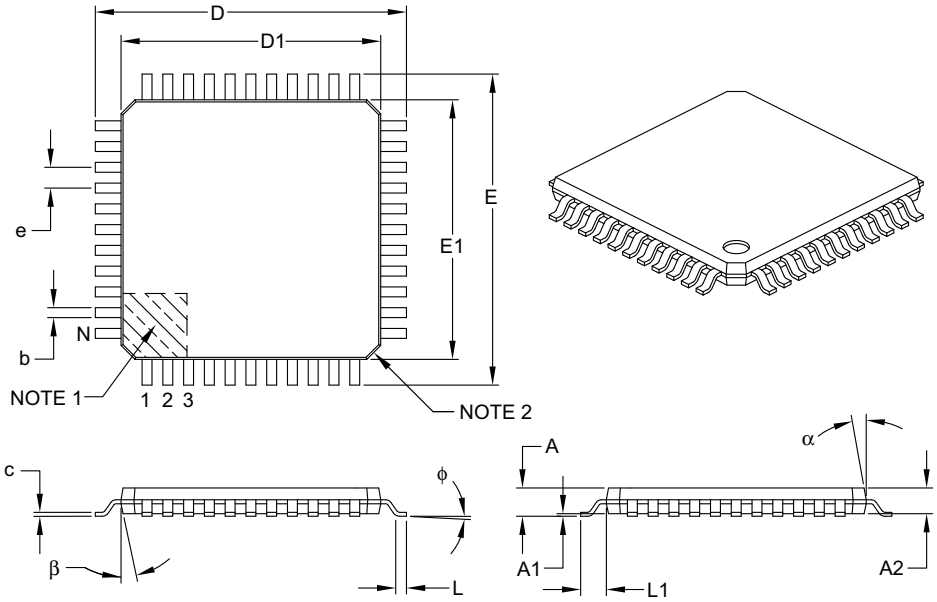
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		44	
Lead Pitch	e		0.80 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B